

*Amended
by Article 191*

CLAIMS

1. A slurry for cutting a silicon ingot, comprising abrasive grains and a basic material, characterized in that:

a content of the basic material is at least 3.5% by mass based on a total mass of a liquid component of the slurry;

the slurry contains organic amine in a mass ratio of 0.5 to 5.0 with respect to water in the liquid component of the slurry; and

pH of the slurry is 12 or more.

2. A method of cutting a silicon ingot using a slurry for cutting a silicon ingot, comprising abrasive grains and a basic material, characterized in that:

a content of the basic material is at least 3.5% by mass based on a total mass of a liquid component of the slurry;

the slurry contains organic amine in a mass ratio of 0.5 to 5.0 with respect to water in the liquid component of the slurry;

pH of the slurry is 12 or more; and

the slurry is used at 65°C to 95°C.